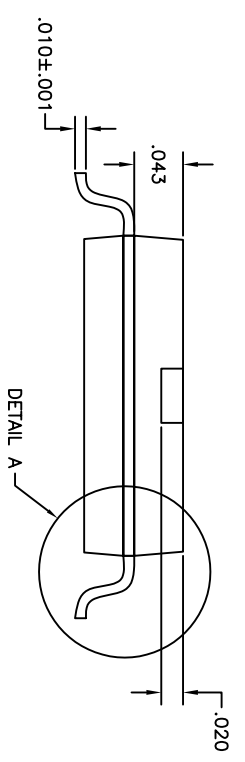
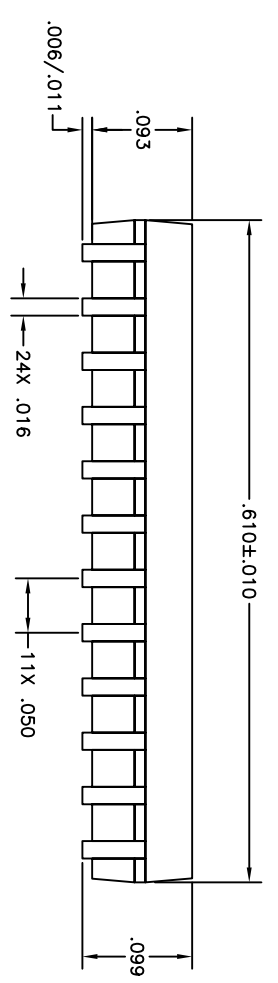
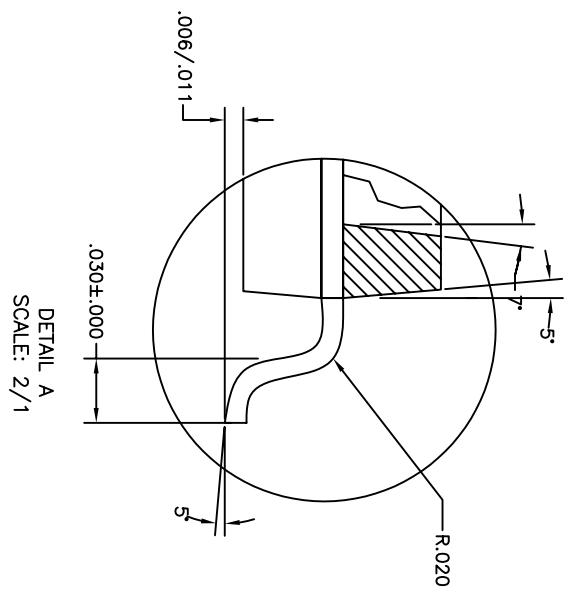
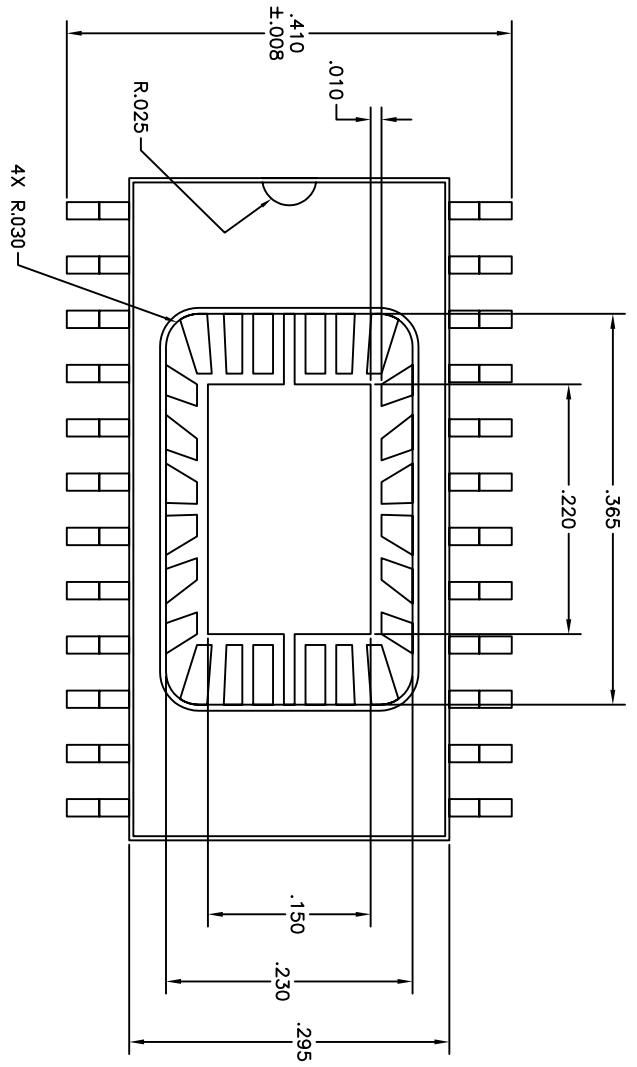


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REVISIONS		APPROVED
ECON NO.	DATE	DESCRIPTION
10515	11/2/05	PRODUCTION RELEASE
		D.BENAVANDO



NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
2. LEADFRAME: COPPER, FH 194.
3. LEAD FINISH: FULL Au PLATE.
4. DIE PAD: .220" x .150".



UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
XXX ± 0.01 XXXXX ± .005
XXXX ± 0.005 ANGLES: ± 1'

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	11/1/05
APP BY	P. FLASKERUD	DATE	11/1/05
CUSTOMER	-----		

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24 Lead 300 mils
SOIC Open-Pak

SIZE	PART NO.	REV
A	SOIC300-24-0P-01	3
SCALE	NONE	
CAD FILE	SOIC300-24-0P-01-R3.DWG	
SHEET	1 OF 1	

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